

L Number	Hits	Search Text	DB	Time stamp
1	879	(chip same substrate) and resin and (die same pressure)	USPAT; US-PGPUB	2004/09/29 17:32
2	54	(chip same substrate) and ((melted or melting) near3 resin) and (die same pressure)	USPAT; US-PGPUB	2004/09/29 16:46
3	47	((chip same substrate) and ((melted or melting) near3 resin) and (die same pressure)) and @ad<20020927	USPAT; US-PGPUB	2004/09/29 16:46
4	25	(chip same substrate) and resin and (die same pressure)	EPO; JPO; DERWENT; IBM TDB	2004/09/29 17:33